TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type(π -MOS IV)

TK09H90A

Switching Regulator Applications

Unit: mm

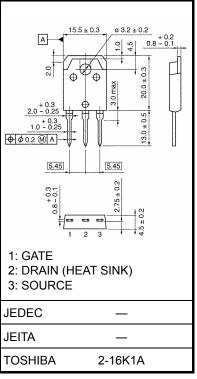
• Low drain-source ON resistance : RDS (ON) = 1.0Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 6S$ (typ.)

• Low leakage current : $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 720 \text{V)}$

• Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteri	stic	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	9	Α	
	Pulse (Note 1)	I _{DP}	27	Α	
Drain power dissipation	n (Tc = 25°C)	P _D	150	W	
Single-pulse avalanche energy (Note 2)		E _{AS}	778	mJ	
Avalanche current		I _{AR}	9	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 3.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

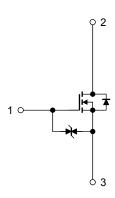
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 17.6 mH, R_G = 25 Ω , I_{AR} = 9 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



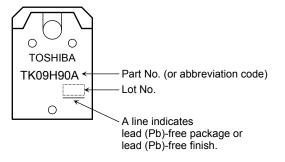
Electrical Characteristics (Ta = 25°C)

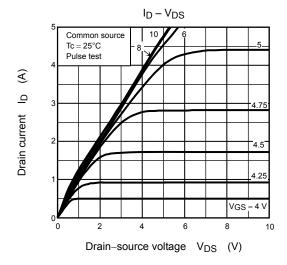
Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 4.0 A	_	1.0	1.3	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 4.0 A	3.5	6.0	_	S
Input capacitano	е	C _{iss}			2200	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	45	_	
Output capacitance		Coss		_	190	_	
Switching time	Rise time	t _r	$V_{GS} = 10V$ $V_{GS} = 100 \Omega$ $V_{OUT} = 100 \Omega$	_	25	_	
	Turn on time	t _{on}		_	65	_	
	Fall time	t _f		_	20	_	ns
	Turn off time	t _{off}	$V_{DD}=400V$ Duty $\leq 1\%$, $t_{\mathbf{W}}=10\mu s$	_	120	_	
Total gate charg plus gate-drain)		Qg			60		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}$		34		nC
Gate-drain ("Miller") charge		Q _{gd}			26	_	

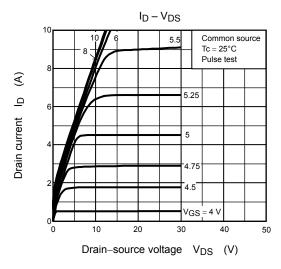
Source-Drain Ratings and Characteristics (Ta = 25°C)

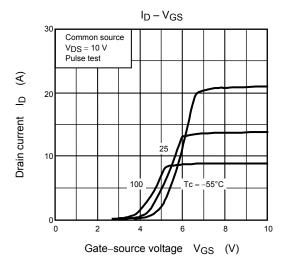
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	9	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	-	-	27	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 9 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 9 A, V _{GS} = 0 V		1450	_	ns
Reverse recovery charge	Qrr	dI _{DR} / dt = 100 A / μs	_	17	_	μC

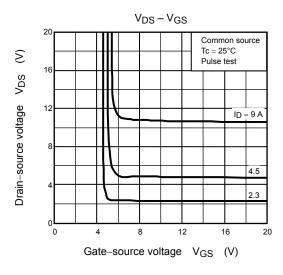
Marking

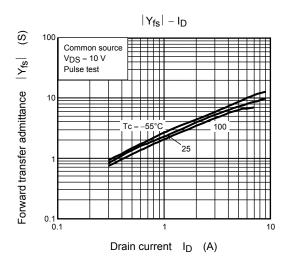


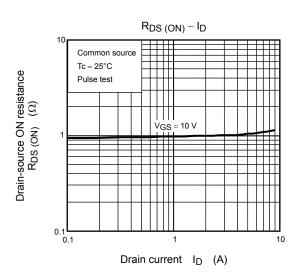




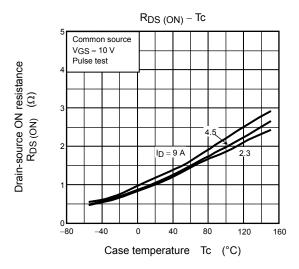


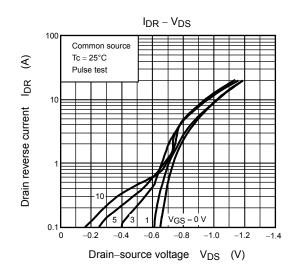


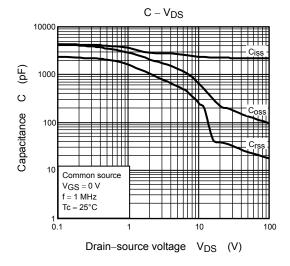


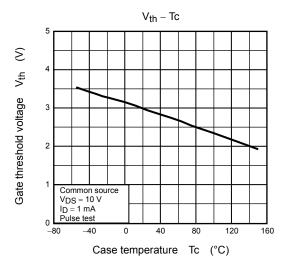


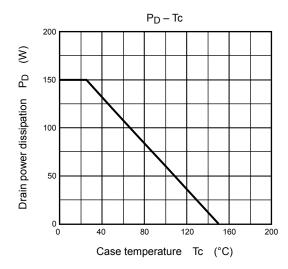
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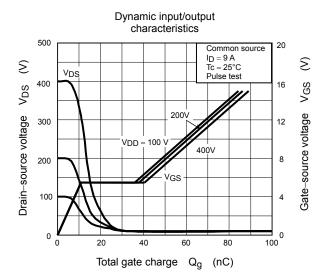


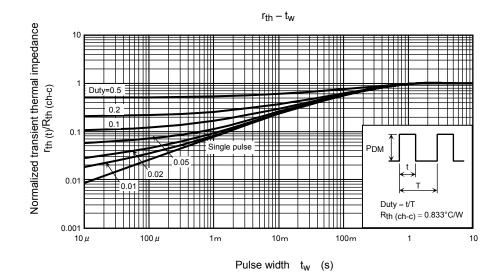


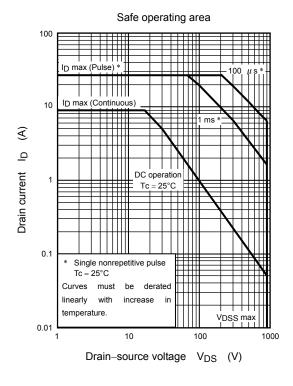


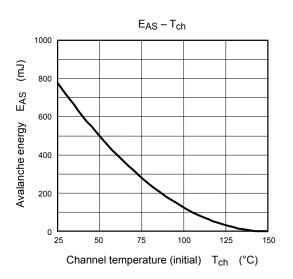


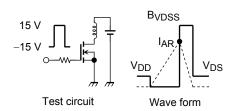












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 17.6~mH \end{aligned} \qquad EAS &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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